PRODUCT NO. * 95706-XXX	STAND OFF DIM"M"(mm)	SOLDER TAIL	DIM "P" (mm)	SHEET NO.	MOUNTING STYLE TO PCB
000	0	R/A	2.8	NO.2	TOP MOUNT 95706-0XX BLACK COLOR PCB
000LF	0	R/A	2.8		
001	0	SMT STAGGERED	//		
002	0	SMT IN LINE	//		
010	4	R/A	2.8	NO.3	
020	5	R/A	2.8		
040	2	R/A	2.5		
010LF	4	R/A	2.8		
020LF	5	R/A	2.8		
040LF	2	R/A	2.5		
500	0	R/A	2.8	NO.4	BOTTOM MOUNT 95706-5XX PCB NATURAL(WHITE)COLOR
500LF	0	R/A	2.8		
501	0	SMT STAGGERED	//		
502	0	SMT IN LINE	//		
510	4	R/A	2.8	NO.5	
520	5	R/A	2.8		
540	2	R/A	2.5		
510LF	4	R/A	2.8		
520LF	5	R/A	2.8		
540LF	2	R/A	2.5		

*95706-X X X X

- LEAD FREE — LF
- SOLDER TAIL
  - 0 : R/A (FOR LOWER & SINGLE)
  - 1 : SMT STAGGERED (FOR LOWER ONLY)
  - 2 : SMT IN LINE (FOR LOWER ONLY)
  - 5 : R/A (FOR UPPER ONLY)
- STAND OFF
  - 0 : 0mm
  - 1 : 4mm
  - 2 : 5mm
  - 4 : 2mm
- MOUNTING STYLE
  - 0 : TOP MOUNTING
  - 5 : BOTTOM MOUNTING

mat'l. code				surface ISO1302	tolerance ISO1101 ISO406	projection	product family MCS
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
B	V00619	RGD	3/30/00	angle	linear 0.X±0.3	MM	68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
C	N05-0048	WB	05/29/03		0.XX±0.13		
D	ELX-N-011445	ZK	04/02/12	0°±2°	0.XXX±0.051	scale 1:1	
				dr S.DUESTERHOEFT 7/20/95			dwg no 95706 sheet 1 of 5 size A4
				engr D.BRANN 7/20/95			
				chr D.BRANN 7/20/95			
				appd D.BRANN 7/20/95			type Product Customer Drawing

sheet index	sheet	1	2	3	4	5
	revision	D	D	D	D	D

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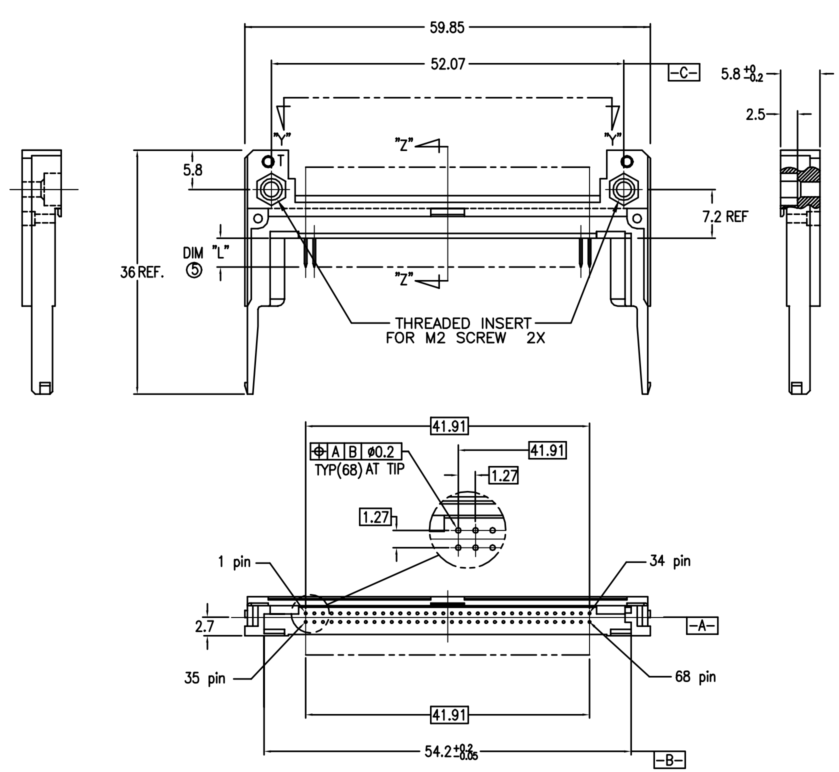
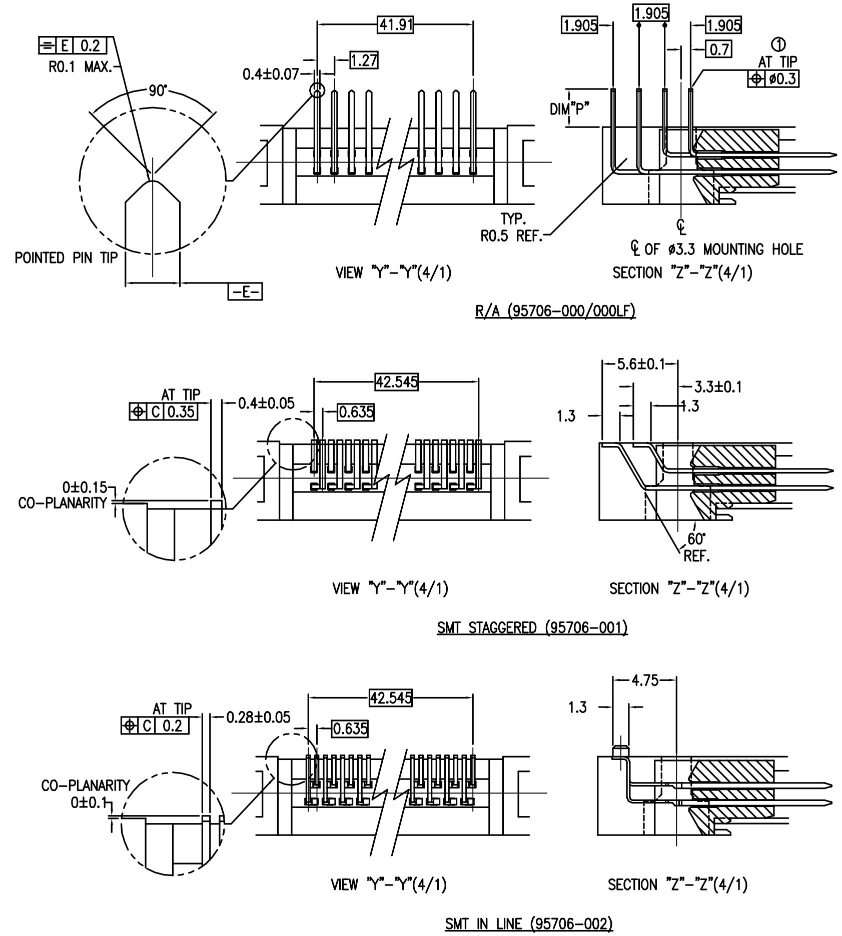
PRODUCT NO.
95706-000/000LF
95706-001
95706-002





NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF
2 SEE TA-946 FOR PCB LAYOUT
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE

④ FINISH
PIN
UNDER PLATING : 0.5µm MIN. Ni
CONTACT AREA : 0.076 µm MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5µm MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5µm MIN. PURE TIN

⑤ SEQUENCE PIN ASSIGNMENT

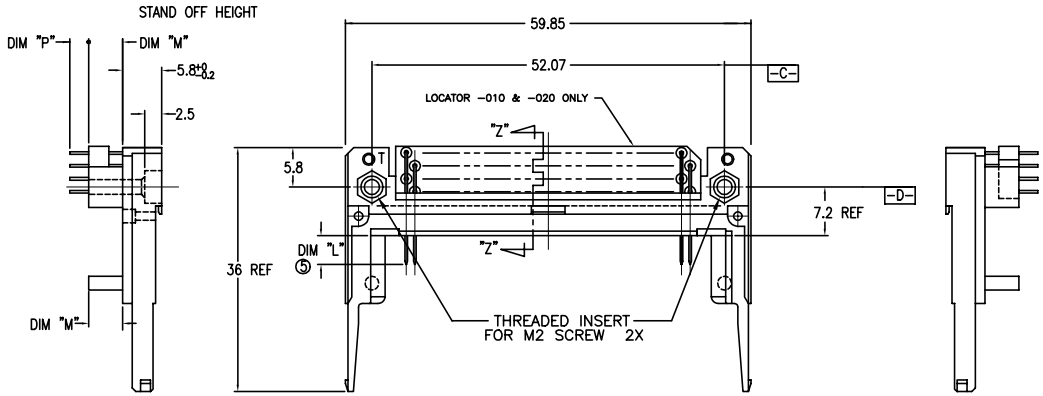
	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

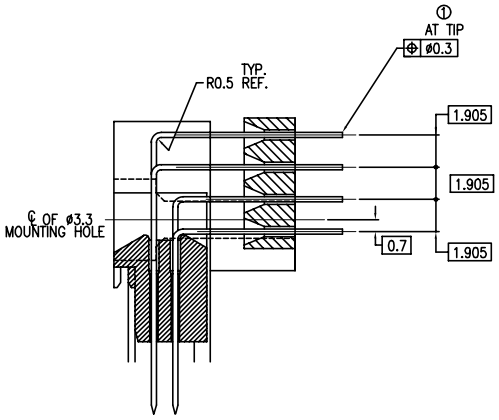
6 GENERAL TOLERANCE : ±0.3
7 IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
9 PRODUCT SPEC:110-263

mat'l. code	surface ISO1302 √	tolerance ISO1101 ISO406	projection	product family MCS
ltr / ecn / nodr / date: D	tolerances unless otherwise specified: angles 0°±2°; linear 0.X±0.3, 0.XX±0.13, 0.XXX±0.051		MM, scale 1:1	title: 68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
	dr S.DUESTERHOEFT 7/20/95			dwg no 95706
	engr D.BRANN 7/20/95			sheet2of5
	chr D.BRANN 7/20/95			size A4
	appd D.BRANN 7/20/95			type Product Customer Drawing
sheet index	revision sheet			

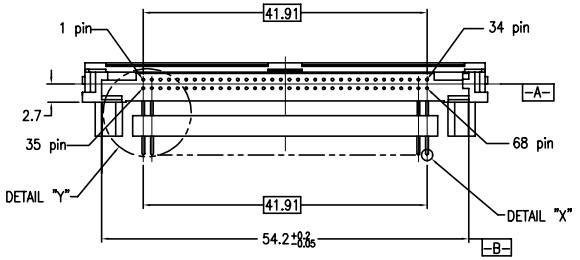
PDS: Rev :D STATUS:Released Printed: Sep 12, 2013

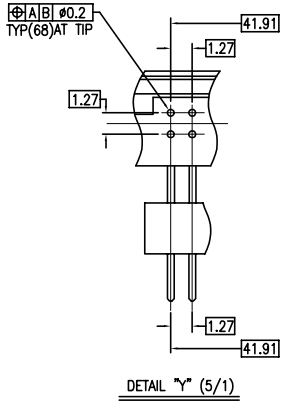
PRODUCT NO.
95706-010/010LF
95706-020/020LF
95706-040/040LF



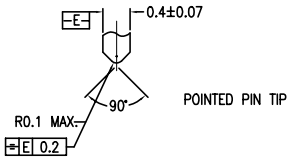


SECTION "Z"-"Z" (5/1)





DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF.
② SEE TA-946 FOR PCB LAYOUT.
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE.
④ FINISH
PIN
UNDER PLATING : 0.5µm MIN. Ni.
CONTACT AREA : 0.076 µm MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5µm MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5µm MIN. PURE TIN

⑤ SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 / 35,51,68

⑥ GENERAL TOLERANCE : ±0.3
⑦ IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
SOLDER TAIL : SMT-IL, SMT-STG CAN RESIST 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
⑧ IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
⑨ PRODUCT SPEC:110-263

mat'l. code				surface ISO1302	tolerance ISO1101 ISO406	projection	product family: MCS
ltr	ecn	nodr	date	tolerances unless otherwise specified			title: 68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
D				angles 0°±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.051	MM	
						scale 1:1	
				dr S.DUESTERHOEFT 7/20/95			dwg no 95706 sheet 3 of 5 size A4
				engr D.BRANN 7/20/95			
				chr D.BRANN 7/20/95			type Product Customer Drawing
				appd D.BRANN 7/20/95			
sheet index	revision sheet						

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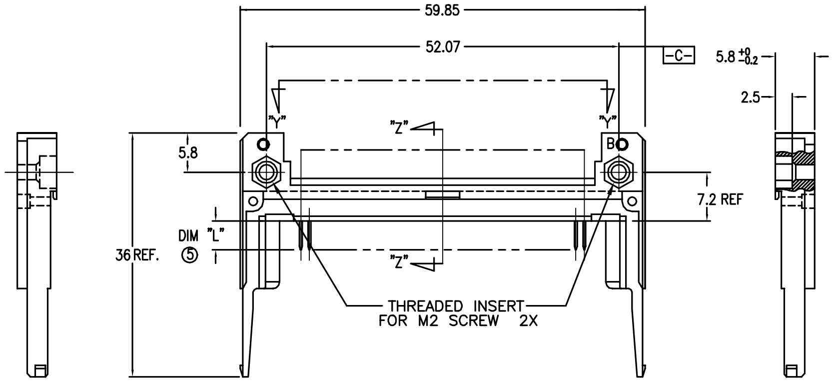
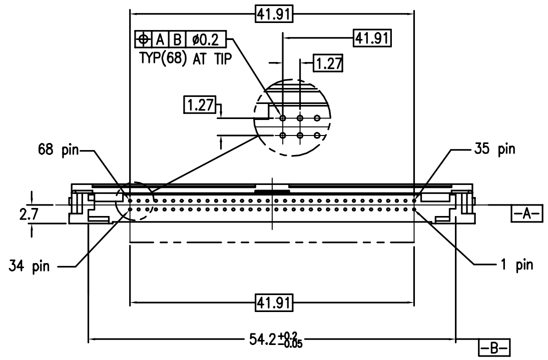
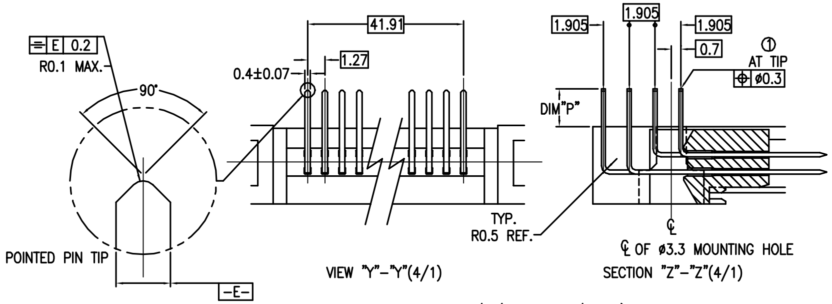
PRODUCT NO.
95706-500/500LF
95706-501
95706-502

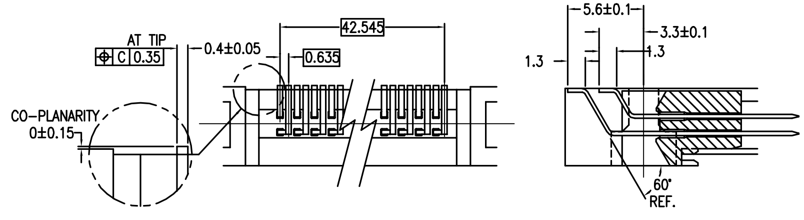






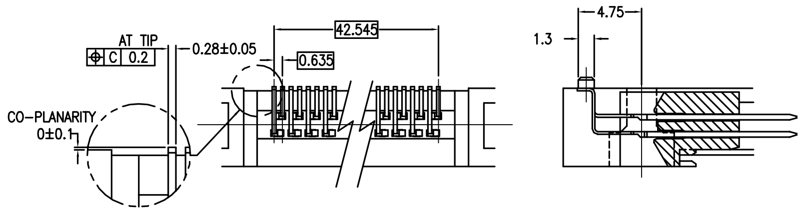
VIEW "Y"-"Y"(4/1) SECTION "Z"-"Z"(4/1)

R/A (95706-500/500LF)



VIEW "Y"-"Y"(4/1) SECTION "Z"-"Z"(4/1)

SMT STAGGERED (95706-501)



VIEW "Y"-"Y"(4/1) SECTION "Z"-"Z"(4/1)

SMT IN LINE (95706-502)

NOTES

① TRUE POSITION IS A FREE GRID TO PIN PATTERN ITSELF
2 SEE TA-946 FOR PCB LAYOUT
③ MATERIAL
HOUSING : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 NATURAL
PIN : PHOSPHOR BRONZE
④ FINISH
PIN
UNDER PLATING : 0.5μm MIN. Ni
CONTACT AREA : 0.076 μm MIN. GOLD

SOLDER AREA(TIN LEAD OPTION): 2.5μm MIN. Sn-Pb
SOLDER AREA(LEAD FREE OPTION): 2.5μm MIN. PURE TIN

⑤ SEQUENCE PIN ASSIGNMENT

	DIM "L"		
	4.25±0.1	3.5±0.1	5.0±0.1
PIN No.	OTHERS	36.67	1,17,34 35,51,68

6 GENERAL TOLERANCE : ±0.3
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SOLDER TAIL : R/A CAN RESIST 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
9 PRODUCT SPEC:110-263

mat'l. code	surface	tolerance	projection	product family
	ISO1302 √	ISO1101 ISO406		MCS
ltr / ecn / nodr / date	tolerances unless otherwise specified			title
D	angle	linear 0.X±0.3	MM	68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE
		0.XX±0.13		
	0°±2°	0.XXX±0.051	scale 1:1	
	dr S.DUESTERHOEFT	7/20/95		dwg no 95706 — sheet 4 of 5 — size A4
	engr D.BRANN	7/20/95		
	chr D.BRANN	7/20/95		
	appd D.BRANN	7/20/95		type Product Customer Drawing
sheet index	revision sheet			

form: A4mmXLc

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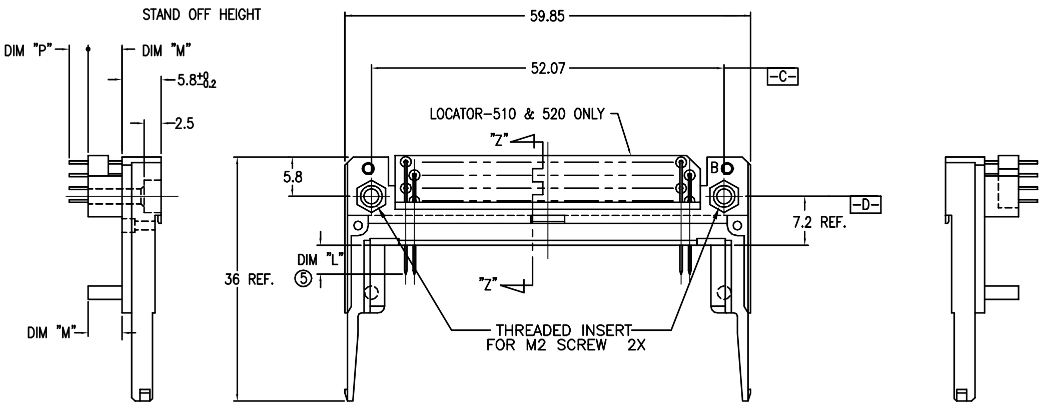
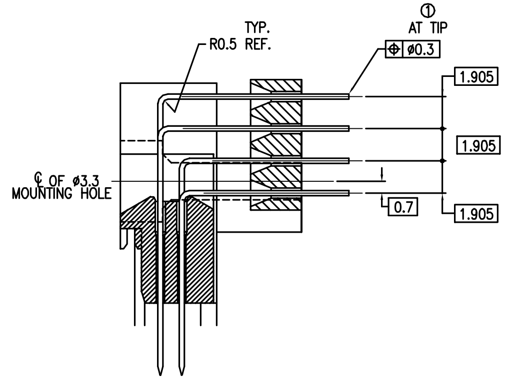
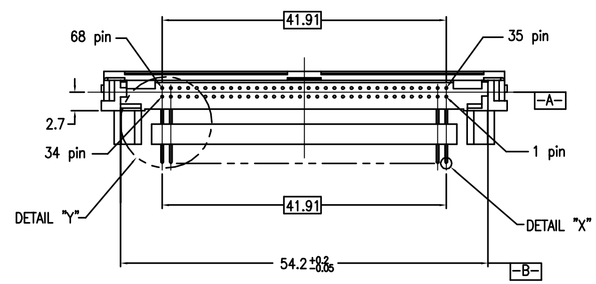
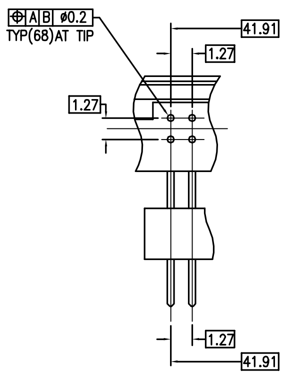
PRODUCT NO.
95706-510/510LF
95706-520/520LF
95706-540/540LF



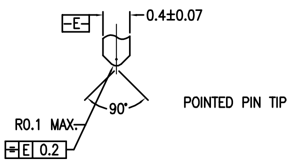


SECTION "Z"-"Z" (5/1)





DETAIL "Y" (5/1)



DETAIL "X" (20/1)
TYP(68)

NOTES

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④ FINISH
PIN
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SOLDER AREA(LEAD FREE OPTION): 2.5µm MIN. PURE TIN
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	DIM "L"		
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8 IF LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
9 PRODUCT SPEC:110-263

mat'l. code	surface ISO1302 √	tolerance ISO1101 ISO406	projection
product family	MCS		
ltr / ecn / nodr / date	D		
tolerances unless otherwise specified	angles 0°±2°	linear 0.X±0.3 / 0.XX±0.13 / 0.XXX±0.051	MM, scale 1:1
title	68 POS. EJECTOR HEADER ASSY. FOR LOW VOLTAGE		
dr	S.DUESTERHOEFT	7/20/95	
engr	D.BRANN	7/20/95	
chr	D.BRANN	7/20/95	
appd	D.BRANN	7/20/95	
dwg no	95706	sheet 5 of 5	size A4
type	Product Customer Drawing		
sheet index	revision sheet		

PDS: Rev :D STATUS:Released Printed: Sep 12, 2013